

Vishay Semiconductors

High Voltage Sinterglas Rectifier

Features

- · High temperature metallurgically bonded construction
- · Cavity-free glass passivated junction
- 1.0 ampere operation at T_{amb} = 100 °C with no thermal runaway
- Typical I_R less than 0.1 μA
- · Hermetically sealed package
- · Capable of meeting environmental standards of MIL-S-19500
- High temperature soldering guaranteed: 350 ° C/ 10 seconds, 0.375 " (9.5 mm) lead length, 5 lbs. (2.3 kg) tension



17031

Mechanical Data

Case: JEDEC DO-204AP Solid glass body

Terminals: Solder plated axial leads, solderable per

MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position: Any

Weight: 560 mg

Parts Table

| Part | Type differentiation | | | | |
|----------|---------------------------|--|--|--|--|
| GI1-1200 | V _{RRM} = 1200 V | | | | |
| GI1-1400 | V _{RRM} = 1400 V | | | | |
| GI1-1600 | V _{RRM} = 1600 V | | | | |

Absolute Maximum Ratings

T_{amb} = 25 °C, unless otherwise specified

| Parameter | Test condition | Sub type | Symbol | Value | Unit |
|---|--|----------|--------------------|-------|------|
| Maximum repetitive peak reverse voltage | | GI1-1200 | V_{RRM} | 1200 | V |
| | | GI1-1400 | V_{RRM} | 1400 | V |
| | | GI1-1600 | V_{RRM} | 1600 | V |
| Maximum RMS voltage | | GI1-1200 | V _{RMS} | 840 | V |
| | | GI1-1400 | V_{RMS} | 980 | V |
| | | GI1-1600 | V_{RMS} | 1120 | V |
| Maximum DC blocking voltage | | GI1-1200 | V_{DC} | 1200 | V |
| | | GI1-1400 | V_{DC} | 1400 | V |
| | | GI1-1600 | V_{DC} | 1600 | V |
| Maximum average forward rectified current | 0.375 " (9.5 mm) lead length at T_{amb} = 75 °C | | I _{F(AV)} | 1.0 | Α |
| Peak forward surge current | 8.3 ms single half sine-wave superimposed on rated load (JEDEC Method) | | I _{FSM} | 30 | Α |

Maximum Thermal Resistance

 T_{amh} = 25 °C, unless otherwise specified

| amb 20 0, amos out of the open | | | | | |
|--------------------------------|----------------|----------|-----------------|---------------|------|
| Parameter | Test condition | Sub type | Symbol | Value | Unit |
| Typical thermal resistance 1) | | | $R_{\theta JA}$ | 55 | °C/W |
| Operating junction and storage | | | T_J, T_{STG} | - 65 to + 175 | °C |
| temperature range | | | | | |

¹⁾ Thermal resistance from junction to ambient and from junction to lead at 0.375 " (9.5mm) lead length, with both leads mounted between heat sinks.

Document Number 86089 www.vishay.com Rev. 1, 12-Nov-02

Vishay Semiconductors



Electrical Characteristics

T_{amb} = 25 °C, unless otherwise specified

| Parameter | Test condition | Sub type | Symbol | Min | Тур. | Max | Unit |
|---------------------------------------|--|----------|-----------------|-----|------|-----|------|
| Maximum instantaneous forward voltage | I _F = 1.0 A | | V _F | | | 1.1 | ٧ |
| | I _F = 3.14 A | | V _F | | | 1.3 | V |
| Maximum DC reverse current | at rated DC blocking voltage T _{amb} = 25 °C | | I _R | | | 10 | μΑ |
| | at rated DC blocking voltage T _{amb} = 100 °C | | I _R | | | 100 | μΑ |
| Typical junction capacitance | V _R = 4.0 V, f = 1 MHz | | CJ | | | 15 | pF |
| Maximum reverse recovery time | I _{FM} = 20 mA, I _R = 2 mA | | t _{rr} | | | 25 | μs |
| Maximum forward recovery time | I _{FM} = 20 mA | | t _{fr} | | | 1.0 | μs |

Typical Characteristics (T_{amb} = 25°C unless otherwise specified)

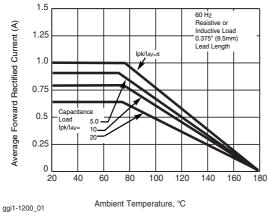


Figure 1. Forward Current Derating Curve

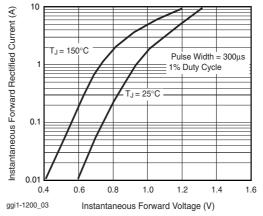


Figure 3. Typical Instantaneous Forward Characteristics

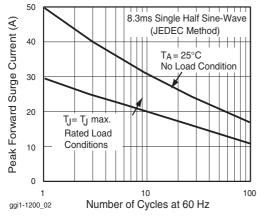


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

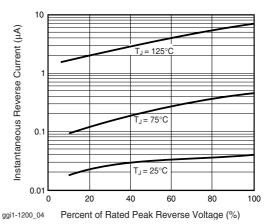


Figure 4. Typical Reverse Characteristics



Vishay Semiconductors

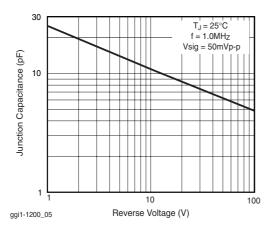
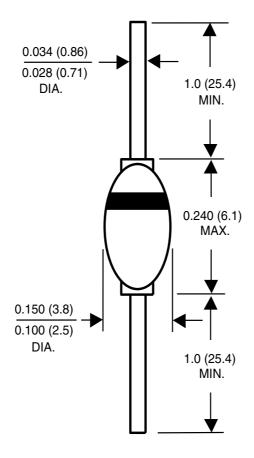


Figure 5. Typical Junction Capacitance

Package Dimensions in mm



Document Number 86089 www.vishay.com

Rev. 1, 12-Nov-02

17030

GI1-1200 to GI1-1600

Vishay Semiconductors



Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

- 1. Meet all present and future national and international statutory requirements.
- 2. Regularly and continuously improve the performance of our products, processes, distribution and operatingsystems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

- 1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
- 2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
- 3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

> Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany Telephone: 49 (0)7131 67 2831, Fax number: 49 (0)7131 67 2423

Document Number 86089 www.vishay.com Rev. 1, 12-Nov-02



Vishay

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.

Revision: 18-Jul-08

Document Number: 91000 www.vishay.com